Product data sheet

1. General description

Hyperfast power diode (Bare die without sawn).

2. Features and benefits

- Low Forward Voltage Drop
- Low leakage current
- · Fast reverse recovery
- Bare die

3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit
V_{RRM}	repetitive peak reverse voltage		[1]		1200		V
$I_{F(AV)}$	average forward current	δ = 0.5; square-wave pulse	[2]		15		Α
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _j = 25 °C	[2]	-	2.50	3.20	V
Dynamic characteristics							
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}$	[2]	-	45	-	ns

4. Ordering information

Table 2. Ordering information

Product type	Orderable part number	Description	Packing method
WB15FC120AL	WB15FC120ALZ	Bare die on wafer	Unsawn wafer, Vacuum packing

5. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage		[1]	1200	V
V_{RWM}	crest working reverse voltage		[1]	1200	V
V_R	reverse voltage	DC	[1]	1200	V
I _{F(AV)}	average forward current	δ = 0.5; square-wave pulse	[2]	15	А
I _{FRM}	repetitive peak forward current	δ = 0.5; t_p = 25 µs; square-wave pulse	[2]	30	А
I _{FSM}	non-repetitive peak forward	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	[2]	180	А
	current	$t_p = 8.3 \text{ ms; } T_{j(init)} = 25 \text{ °C; sine-wave pulse}$	[2]	200	А
T _j	junction temperature			-40 to 175	°C

6. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics						
V _F	forward voltage	I _F = 15 A; T _j = 25 °C	[2]	-	2.50	3.20	V
		I _F = 15 A; T _j = 150 °C	[2]	-	2.00	-	V
I _R	reverse current	V _R = 1200 V; T _j = 25 °C	[1]	-	-	100	μA
		V _R = 1200 V; T _j = 150 °C	[2]	-	-	500	μA
Dynamic	characteristics						
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}$	[2]	-	45	-	ns
		$I_F = 15 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}$	[2]	-	61	-	ns

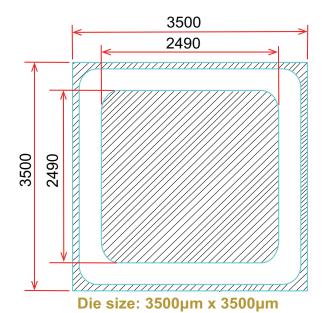
Notes:

Product data sheet

^[1] means that parameter are 100% test at T_{amb} = 25°C [2] means that the guaranteed ratings and parameter limits will depend on the assembled structure. When correctly assembled with suitable die bonding and wire bonding, the device will have ratings and characteristics guaranteed in this data sheet, similar to the assembled devices.

MECHANICAL PATAMETER			
Chip size	3.5 x 3.5	mm ²	
Anode pad size	2.49 x 2.49	mm²	
Area total / active	12.5 / 6.2	mm ²	
Thickness	300	μm	
Wafer size	125	mm	
Max possible chips per wafer	860	pcs	
Passivation	P.E.C.V.D./ Planar		
Front metal	Al		
Back metal	tal Ti Ni Ag		

CHIP LAYOUT



7. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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For more information, please visit: http://www.ween-semi.com
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